Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2736	semiconductor and (package with stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 13:59
S2	1275	S1 and (wire adj bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S3	467	S2 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S4	305	S3 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S5	250	S4 and die and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	.2004/12/06 17:57
S6	103	S5 and (package and stacked).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 17:57
S7	34	S6 and (package and stacked and (wire adj bond\$3)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 09:35
S8	2	("5763913").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF ·	2004/12/07 09:35
S9	1534	semiconductor and (package with stacked) and (substrate with (chip or die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S10	937	S9 and (wire adj bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00

S11	428	S10 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35
S12	284	S11 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35
S13	124	S12 and (package and stacked). ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:01
S14	50	S13 and (wire).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:01
S15	10	("20040063246" "5637916" "6072122" "6222265" "6281581" "6410981" "6545365" "6569712" "6593647" "6593662").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:02
S16	57	("4954878" "5099306" "5109320" "5128831" "5222014" "5252857" "5291061" "5300801" "5323060" "5403784" "5422435" "5434745" "5466627" "5473814" "5497082" "5495398" "5494841" "5495398" "5498905" "5506756" "5508565" "5512765" "5512780" "5512765" "5535101" "5594275" "5639696" "5705858" "5715144" "5728606" "5729440" "6051878").PN. OR ("6222265").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:34
S17	486	S9 and ((wire adj bond\$3) with substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:34
S18	273	S17 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35

S19	189	S18 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2004/12/07 14:47
S20	106	S19 and heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:57
S21	2	("5373189").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 14:57
S22	46	("5373189"):URPN.	USPAT	OR	ON	2004/12/07 14:58